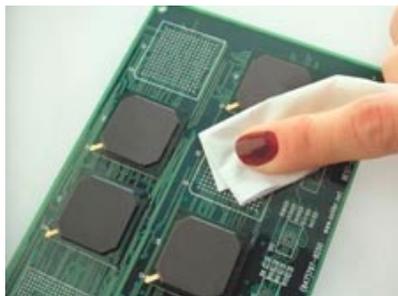


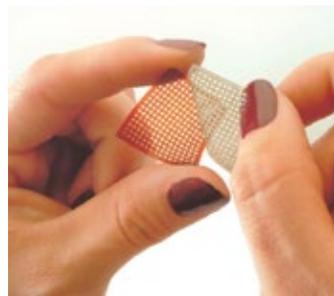
STENCIL QUICK USER INSTRUCTIONS

1. Remove part

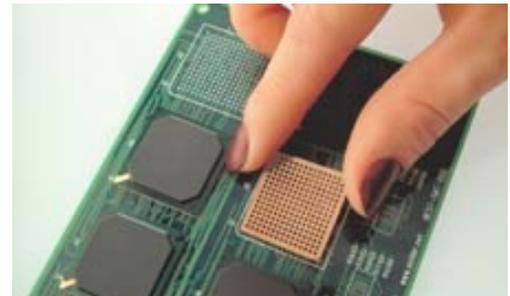
2. Dress site by wicking off residual solder with solder wick or de-soldering tool.



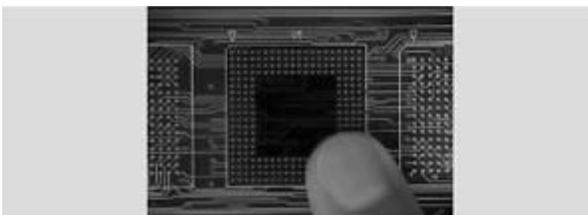
3. Clean site.



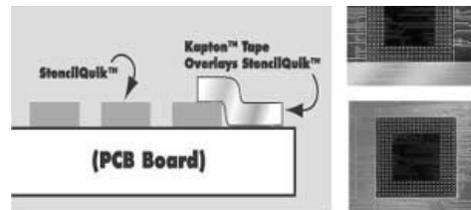
4. Remove release liner from back of SolderQuick™ stencil.



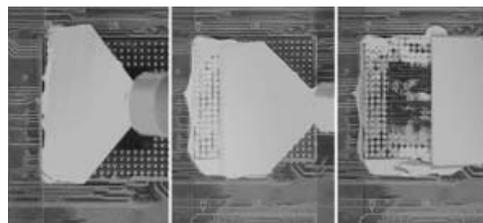
5. Align StencilQuick™ by positioning the diagonally opposite corner apertures over the corresponding pads. Note: Ensure that the pads are centered in the apertures.



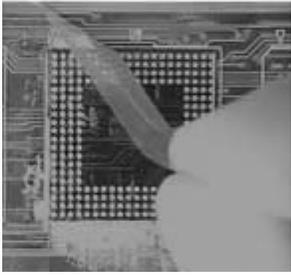
6. Place the StencilQuick™ on the board applying pressure to the stencil to activate the adhesive. Note: Do not apply pressure until satisfied with alignment.



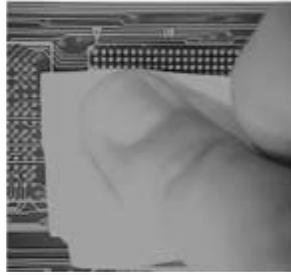
7. Tape off the area around the periphery of the part site with Kapton™ tape. Note: Ensure that the tape overlaps the outside edge of the StencilQuick™



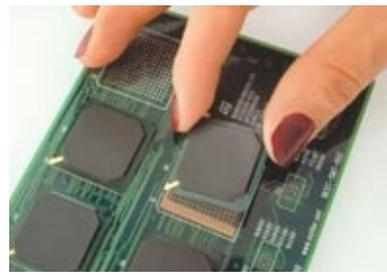
8. Squeegee solder paste across the top of the StencilQuick™ making sure all of the apertures are filled.



9. Remove the masking tape applied to the periphery of the reworked area applied in step#7



10- Wipe of the excess solder paste from the top of the StencilQuick™ with a lintfree wipe.



11- Gently place the properly conditioned part aligning the balls of leads on the part with the filled apertures.



12. Reflow the part.